



RFBLN Series – 1608(0603)- RoHS Compliance

MULTILAYER CERAMIC BALUN TRANSFORMER

2.5 GHz Wi-Max Band Working Frequency

P/N: RFBLN16082G5W0T

*Contents in this sheet are subject to change without prior notice.

Approval sheet



- 1. Multilayer LTCC (Low Temperature Cofired Ceramics) Technology
- 2. Miniatured Size $1.6 \times 0.8 \times 0.7 \text{ mm}^3$
- 3. Low Insertion Loss reduces power consumption
- 4. Low inband Amplitude and Phase imbalance enable high performance wireless system operation.
- 5. Enable for DC Biasing of PA or Mixer
- 6. Suitable for 2.5 GHz Working Frequency Operation
- 7. Special Balance/ Unbalance impedance is upon requested.

APPLICATIONS

1. Wi-Max (Worldwide interoperability for Micrive Access) RF Application

CONSTRUCTION



PIN	Connection			
P1	Unbalanced port			
P2	DC or GND			
P3	Balanced port			
P4	Balanced port			
P5	GND			
P6	NC			

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DIMENSIONS



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ELECTRICAL CHARACTERISTICS

RFBLN16082G5W0T	Specification
Frequency range	2500± 200 MHz
Insertion Loss	1.1 dB max
VSWR	2.0 max
Impedance (Unbalanced)	50 Ω
Impedance (Balanced)	100 Ω
Phase Difference	180° ± 10°
Amplitude Difference	2.0 dB Max
Typical Electrical Chart	

Typical Electrical Chart



SOLDER LAND PATTERN



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RELIABILITY TEST

Test item	Test condition / Test method	Specification	
Solderability JIS C 0050-4.6	*Solder bath temperature : $235 \pm 5^{\circ}$ C	At least 95% of a surface of each terminal	
JESD22-B102D	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.	
	Solder : Sn3Ag0.5Cu for lead-free		
Leaching (Resistance to dissolution	*Solder bath temperature : $260 \pm 5^{\circ}$ C *Leaching immersion time : 30 ± 0.5 sec	Loss of metallization on the edges of each electrode shall not exceed 25%.	
of metallization) IEC 60068-2-58	Solder : SN63A		
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : $120~150^{\circ}$ C,	No mechanical damage.	
	1 minute.	Samples shall satisfy electrical specification	
	*Solder temperature : 270±5°C	after test.	
	*Immersion time : 10±1 sec	Loss of metallization on the edges of each	
	Solder : Sn3Ag0.5Cu for lead-free	electrode shall not exceed 25%.	
	Measurement to be made after keeping at		
	room temperature for 24±2 hrs		
Drop Test JIS C 0044 Customer's specification.	*Height : 75 cm *Test Surface : Rigid surface of concrete or steel.	No mechanical damage. Samples shall satisfy electrical specification after test.	
	*Times : 6 surfaces for each units ; 2 times for each side.		
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.	
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and	No mechanical damage. Samples shall satisfy electrical specification after test.	
	then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours		

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Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
JIS C 0025	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency : 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude : 1.5mm	Samples shall satisfy electrical specification
	*Test times ÷ 6hrs.(Two hrs each in three	after test.
	mutually perpendicular directions)	
High temperature	*Temperature : 85°C±2°C	No mechanical damage.
JIS C 0021	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
Humidity	*Humidity : 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification
JIS C 0022	*Time : 1000+24/-0 hrs.	after test.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	ℜ 500hrs measuring the first data then	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
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SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,



Fig 2. Infrared soldering profile

ORDERING CODE

RF	BLN	1608	2G5	w	0	Т
Walsin	Product	Dimension code	Central Frequency	Application	Specification	Packing
RF: RF	Code	Per 2 digits of Length,	2G5: 2.5GHz	W : Wi-Max	Design Code	T : Reeled
/Pb free	BLN :	Width:				
device	BALUN	e.g. :				
		1608 =				
		Length 16,				
		Width 08,				

PACKAGING

Paper Tape specifications (unit :mm)



Index	Ao	Во	ΦD	Т	W
Dimension (mm)	0.975 ± 0.05	1.76 ±0.05	1.55 + 0.05	0.75 ± 0.03	8.0 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05

Reel dimensions



Taping Quantity: 4000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.
 - Temperature : -10 to +40°C
 - Humidity : 30 to 70% relative humidity
 - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
 - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
 - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
 - Products should be storage under the airtight packaged condition.